



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Hyun-Ho Kim, et al.

Serial No.

10/620,745

Examiner:

not yet assigned

Filed:

July 15, 2003

Group Art Unit:

2811

For:

IN-LINE DIE ATTACHING AND CURING APPARATUS

FOR A MULTI-CHIP PACKAGE

Confirmation No.

8977

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:	
This In:	formation Disclosure Statement is submitted:
\boxtimes	under 37 CFR 1.97 (b); or (Within three months of filing national application; or date of entry of International application;
or	before mailing date of first office action on the merits; whichever occurs last)
	under 37 CFR 1.97 (c) together with either a: Statement under 37 CFR 1.97 (e), or
	a \$180 fee under 37 CFR 1.17 (p); or (After mailing of first Office Action, but prior to Notice of Allowance or Final Office Action)
	under 37 CFR 1.97 (d) together with:
	Statement under 37 CFR 1.97 (e), and a \$180.00 fee set forth in 37 CFR 1.17 (p). (Filed after final action or notice of allowance, whichever occurs first, but before payment of
the issue fee)	
copies of patent may be material with 37 CFR 1	Applicant(s) submit herewith Form PTO 1449- Information Disclosure Citation together with s, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) to the examination of this application and for which there may be a duty to disclose in accordance 56.

It is requested that the information disclosed herein be made of record in this application.

Any deficiency or overpayment should be charged or credited to deposit account number 13-1703. A duplicate copy of this sheet is enclosed.

Customer No. 20575

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

Alan T. McCollom Reg. No. 28,881

MARGER JOHNSON & McCOLLOM, P.C. 1030 SW Morrison Street Portland, OR 97205 503-222-3613

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA

22313-1450

Date: October 31, 2003

Adrienne Chocholak

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INFORMATION DISCLOSURE CITATION FORM PTO-1449 (Modified)

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Examiner:										